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“Unprecedented Innovation” To Be Driven By The Next Generation of Semiconductor Manufacturing

Top semiconductor executives discuss “Semiconductor Business: Inflections Beyond Scaling” at 2016 Symposia on VLSI Technology & Circuits panel session...

HONOLULU, HI (MAY 10, 2016) – The next generation of semiconductor design, development, and manufacturing faces a number of inflection points beyond geometric scaling. New technologies for sensing, positioning, energy-awareness, predictive systems, and their integration promise to open wider applications and the potential for exponential growth in the semiconductor industry. Bringing these new technologies from research to reality will require an unprecedented degree of innovation to meet the technical and business challenges posed by this opportunity.

Senior industry executives will deliberate on these opportunities – and challenges – in a panel session at the 2016 Symposia on VLSI Technology & Circuits, a premiere international conference on semiconductor technology that defines the pace, progress and evolution of microelectronics, scheduled from June 13-17, 2016 in Honolulu, Hawaii.

Scheduled for Wednesday, June 15 evening, the executive panel session is entitled “**Semiconductor Business: Inflections Beyond Scaling**,” and is part of the Symposia’s overall theme “**Inflections for a Smart Society**,” reflecting the semiconductor industry’s transition point as the pace of scaling slows and heterogeneous integration technologies rise to meet the challenges of an increasingly connected society (Internet of Things).

Moderated by Dan Hutcheson, CEO & Chairman of VLSI Research Inc. and author of *The Chip Insider*[®], the panel is comprised of senior industry executives, including:

- Mike Cadigan, senior VP, global sales & business development, GLOBALFOUNDRIES
- Tze-Chiang Chen, IBM Fellow, IBM TJ Watson Research Center, IBM
- SungJoo Hong, executive VP & head of R&D, SK Hynix
- Steve Lloyd, VP, engineering & new product development, InvenSense
- Marie-Noelle Semaria, CEO, CEA-LETI

“The systems for the new connected society will require ultra-low power, smart energy sources and management, ‘always-on’ sensing, universal connectivity, as well as vast amounts of embedded and discrete memory – all packaged in ever-smaller form factors,” observed Hutcheson. “The investment to develop the technologies around the IoT, along with the standards, security protocols, inter-platform operability for them to seamlessly function will be

significant, and will require unprecedented innovation and new collaboration models between device and systems designers and manufacturers.”

“Self-driving automobiles, next-generation 5G networks, machine learning, neural computing, virtual/immersive reality systems and other emerging technology inflections will drive the need to establish new business models and new infrastructure to be successfully deployed. The technical and economic implications of these changes make for an interesting discussion,” said Raj Jammy, General Chair of the 2016 VLSI Technology Symposium.

More information about the executive panel session is available here:

<http://vlsisymposium.org/program/>

The annual Symposia on VLSI Technology & Circuits have made this industry transition its focal point, with the conference theme serving as the thread connecting the program elements. This year, the annual Symposia will be held at the Hilton Hawaiian Village, Honolulu, Hawaii from June 13-16, 2016 (Technology) and June 14-17, 2016 (Circuits). Held together since 1987, the Symposia provide a unique opportunity for the world’s top device technologists, circuit and system designers to exchange leading edge research on microelectronics technology, with alternating venues between Hawaii and Japan.

Sponsoring Organizations

The Symposium on VLSI Technology is sponsored by the IEEE Electron Devices Society and the Japan Society of Applied Physics, in cooperation with the IEEE Solid State Circuits Society.

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Further Information, Registration and Program Details

Visit: <http://www.vlsisymposium.org>.

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